



XTMT03N170L

30V N-ch Planar MOSFET

Product Description

BV_{DSS}	30	V
I_D	170	A
$R_{DS(ON), Typ.}$	0.97	m Ω

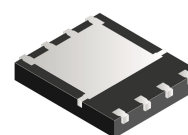
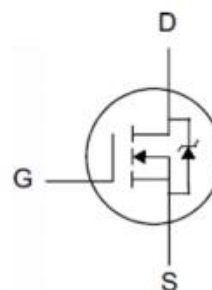
General Features

- Excellent gate charge x RDS(on) product(FOM)
- $R_{DS(ON), typ.} = 0.97m\Omega @ V_{GS} = 10V$
- 150 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Applications

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

封装 Package



PDFN 5×6

Device	Package	Marking
XTMT03N170L	PDFN5*6	XTMT03N170L

Absolute Maximum Ratings $T_j = 25^\circ\text{C}$

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-to-Source Voltage	30	V
V_{GSS}	Gate-to-Source Voltage	± 20	
I_D	Continuous Drain Current	170	A
I_{DM}	Pulsed Drain Current at $V_{GS} = 10V$	680	
E_{AS}	Single Pulse Avalanche Energy	1350	mJ
P_D	Power Dissipation	135	W
	Derating Factor above 25°C	1.08	W/ $^\circ\text{C}$
$T_J \& T_{STG}$	Operating and Storage Temperature Range	-55 to 150	$^\circ\text{C}$

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.



Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.926	$^{\circ}\text{C/W}$

Electrical Characteristics $T_j=25^{\circ}\text{C}$

OFF Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
BV_{DSS}	Drain-to-Source Breakdown Voltage	30	-	-	V	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$
I_{DSS}	Drain-to-Source Leakage Current	-	-	1	μA	$V_{DS}=30\text{V},$ $V_{GS}=0\text{V}, T_J=25^{\circ}\text{C}$
		-	-	1.5	μA	$V_{DS}=30\text{V},$ $V_{GS}=0\text{V}, T_J=55^{\circ}\text{C}$
I_{GSS}	Gate-to-Source Leakage Current	-	-	± 80	nA	$V_{GS}=\pm 5\text{V}, V_{DS}=0\text{V}$
		-	-	± 100		$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$

ON Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	0.75	0.97	1.2	$\text{m}\Omega$	$V_{GS}=10\text{V}, I_D=20\text{A}$
		1	1.25	1.5	$\text{m}\Omega$	$V_{GS}=4.5\text{V}, I_D=20\text{A}$
$V_{GS(TH)}$	Gate Threshold Voltage	1.0	1.5	2.0	V	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$
gfs	Forward Transconductance	-	80	-	S	$V_{DS}=5\text{V}, I_D=20\text{A}$



Dynamic Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
C _{iss}	Input Capacitance	-	5300	6890	pF	V _{GS} =0V, V _{DS} =15V, f=1.0MHz
C _{rss}	Reverse Transfer Capacitance	-	1800	2600		
C _{oss}	Output Capacitance	-	100	200		
Q _g	Total Gate Charge	-	90	126	nC	V _{DS} =15V, I _D =20A, V _{GS} =10V
Q _{gs}	Gate-to-Source Charge	-	12	18		
Q _{gd}	Gate-to-Drain (Miller) Charge	-	13	19.5		

Resistive Switching Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
t _{d(ON)}	Turn-on Delay Time	-	12	-	nS	V _{DD} =15V, I _D =20A V _{GS} =10V, R _G =1.6 Ω
t _{rise}	Rise Time	-	6.5	-		
t _{d(OFF)}	Turn-Off Delay Time	-	48	-		
t _{fall}	Fall Time	-	7.5	-		

Source-Drain Body Diode Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
V _{SD}	Diode Forward Voltage	-	-	1.2	V	I _S =20A, V _{GS} =0V
I _S	Diode Forward Current	-	-	170	A	
t _{rr}	Reverse Recovery Time	-	-	30	ns	T _J = 25° C, I _F = I _S di/dt = 100A/ μ s
Q _{rr}	Reverse Recovery Charge	-	-	110	uC	

[1] Pulse width ≤ 380 μs; duty cycle ≤ 2%



Typical Characteristics(Cont.)

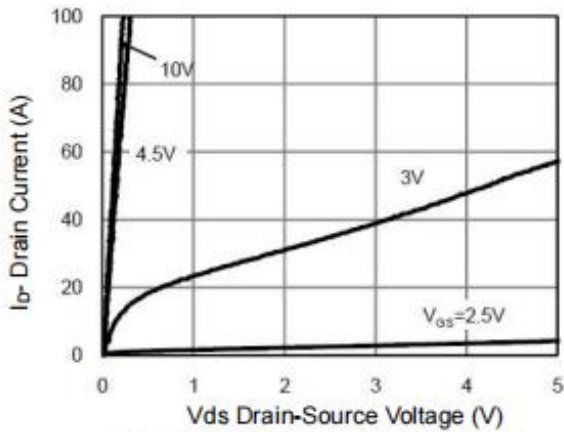


Figure 1 Output Characteristics

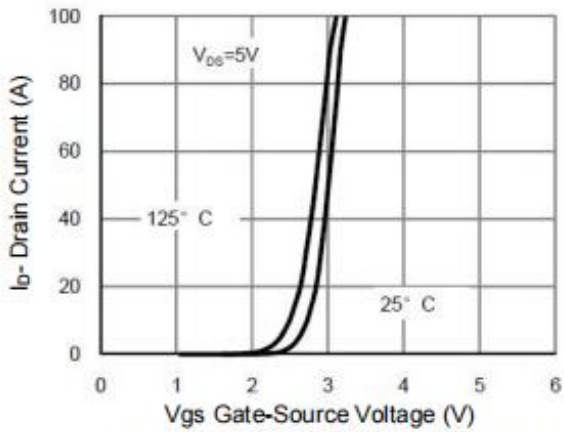


Figure 2 Transfer Characteristics

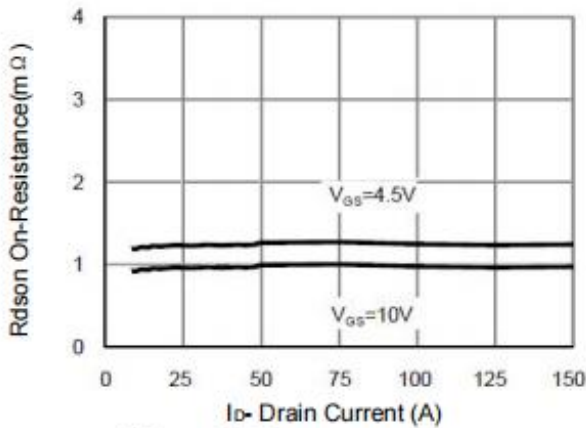


Figure 3 Rdson- Drain Current

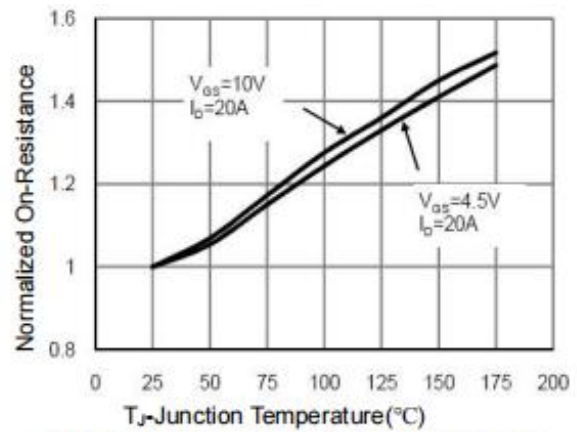


Figure 4 Rdson-Junction Temperature

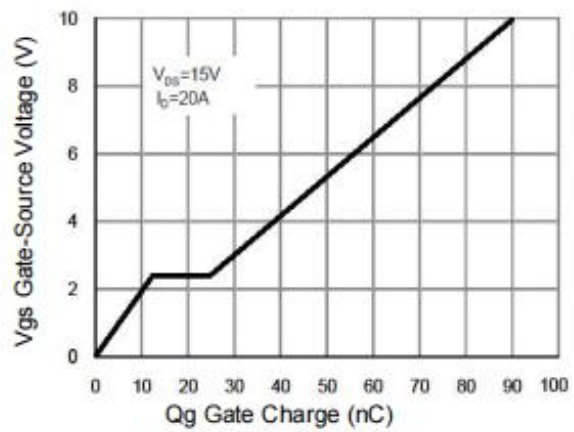


Figure 5 Gate Charge

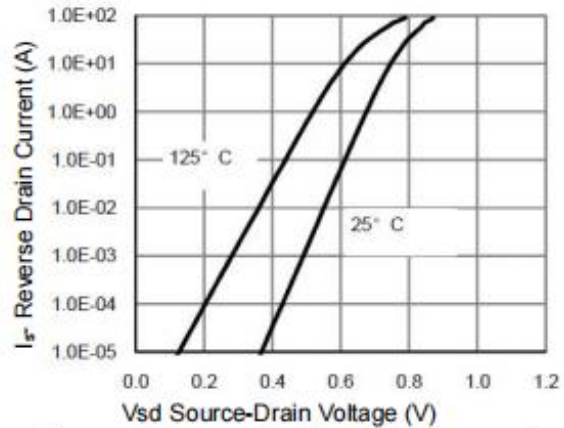


Figure 6 Source- Drain Diode Forward



Typical Characteristics(Cont.)

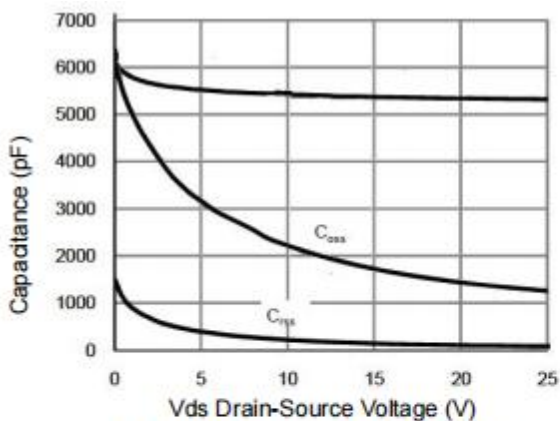


Figure 7 Capacitance vs Vds

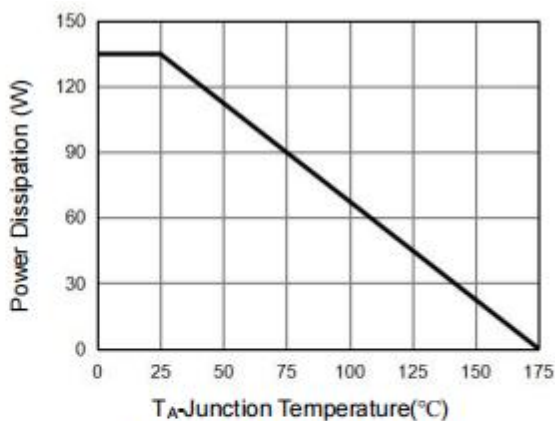


Figure 9 Power De-rating

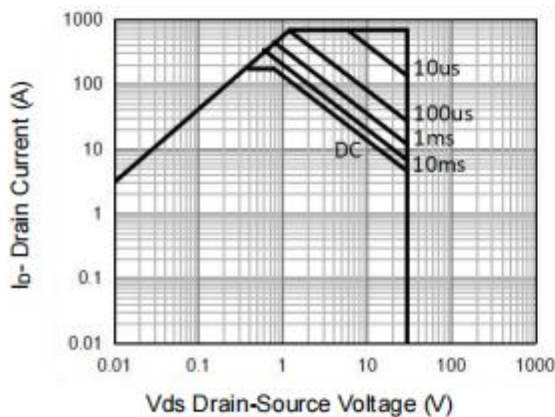


Figure 8 Safe Operation Area (Notes)

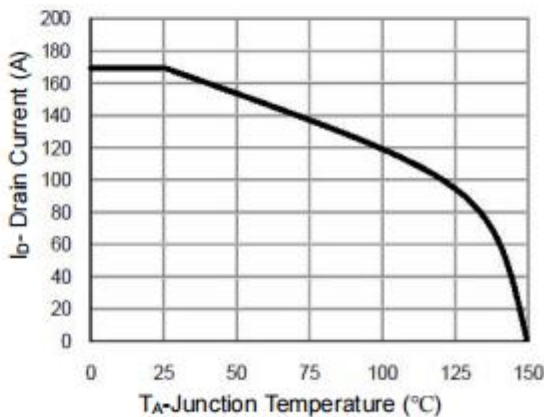


Figure 10 Current De-rating

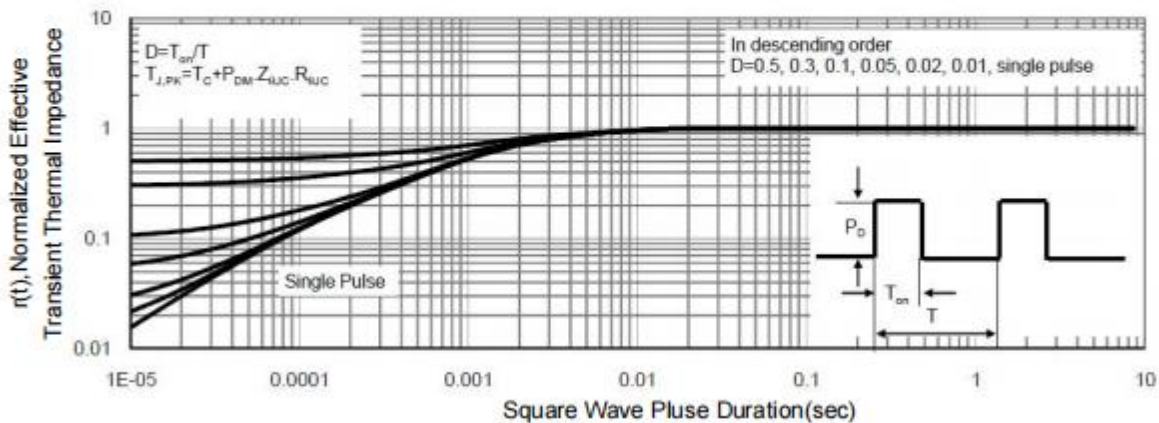


Figure 11 Normalized Maximum Transient Thermal Impedance